

Headquarters

AE Advanced Engineering
PO Box 282
M. 47, Nahalal 106000
Israel
Tel: +972-4-6042604
Fax: +972-4-6042607
e-mail: sales@eshal.com

Additional Features

1. UVA LED high intensity irradiation light source.
2. On-line UV intensity metering.
3. Process Log and System Log saved to database for quality and maintenance reporting.
4. Special operation mode for recipe formulation and system testing.
5. User configurable Signal Tower lamps.

Typical UV Curing Process Sequence

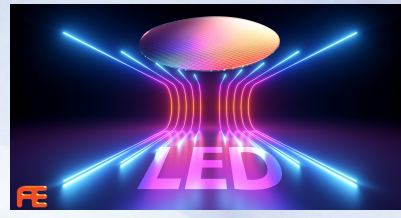
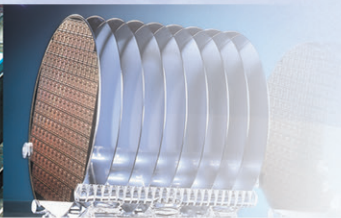
1. Wafer cassette containing frames with mounted substrates awaiting UV exposure is placed on cassette loading adaptor.
2. Operator selects desired pre-programmed UV exposure recipe (Tape Type) on the Flat Panel Display interface and starts the process cycle.
3. System scans the wafer cassette to determine which slots are populated. This information is used to optimize material handling during the processing cycle.
4. System automatically transports wafer/frames from the cassette to the UV exposure station, where each frame is in turn irradiated according to the process recipe.
5. During the UV exposure of a frame, the next frame is positioned in the standby position, so that as the completed frame is transported back to its original location in the cassette, the next frame receives UV exposure. In this manner, total process cycle time is optimized.
6. When all wafer frames have been exposed and returned to the cassette, the system indicates the process completion Flat Panel Display and the system signal lamp. Operator can now remove cassette to complete the process cycle.

Specifications

Wafer sizes	6" & 8"
Frame/Cassette types	Standard Disco/K&S 6" and 8"
Effective UV wavelength	365 nm
Throughput	<6 minutes per 25-frame cassette
Control unit	Pentium 4 PC, Windows™ XP Operating System
Electrical utility	110 or 240 Vac, 50/60 Hz
Power	1200 W (max.)
Air	72 p.s.i. (5 bar) c.d.a.
Dimensions	(HxWxD) 45" x 20" x 40" (114 x 50 x 100cm.)
Footprint	20" x 40" (50 x 100 cm.)
Weight	209 lbs. (95 kg)

- Specifications may be changed without prior notice.
- Test Conditions:
Tape curing energy required = 200 mJ/cm², with silicon wafer.
- All other countries and general enquiries:
E-mail: sales@eshal.com

Visit us on the web: www.eshal.com



Model UV-9200-L Automatic UV Curing System – LED Unique High-Intensity UVA Light Source

General Description

The UV-9200-L is a fully automatic post-dicing UV curing system for the efficient and reliable processing of wafers up to 8" diameter mounted on dicing frames. The UV-9200-L is based on AE's field-proven UV curing technology, providing PC-control ease-of-use and low cost-of-operation.

Windows Interface

The UV-9200-L employs the simple-to-use and familiar Windows software interface. The Flat Panel monitor displays UV intensity, irradiation time and other process parameters on-line, for comprehensive visual monitoring of system operation. Authorized operators (password protected) can easily edit process parameters via the convenient Setup screen.

UV-9200-L Features-at-a-Glance

- UVA LED high intensity irradiation light source
- Fully automatic.
- Continuous processing cycle.
- PC with familiar Windows software interface.
- Low Cost-of-Ownership.
- Safe, ozone-free UV irradiation source.
- Processes 6" and 8" wafer frame/cassette.
- Economical footprint (50 x 100 cm).

Fully Automatic

There is no operator contact with wafer frame during processing. Operator inserts wafer cassette into system, initiates process, then removes completed wafer cassette.

Continuous Processing Cycle

No wasted handling time between UV exposure of individual wafer frames. Intelligent transport system maintains continual wafer frame presence over UVA LED source.

Windows Interface

Simple-to-use, familiar Windows software interface. Flat Panel Display shows UV intensity, process time, etc. Authorized operator can edit process parameters via Setup screen.

Safe, Ozone-free UV Light Source

Uses optimized wavelength for UV curing process. UVA LED source do not require special cooling or exhaust systems to counteract harmful ozone emissions. Provides safe operating environment and economical utility requirements.

Uses Standard 6" and 8" Wafer Frame/Cassette

Works with standard Disco/K&S wafer frames, or equivalent. Special cassette and wafer frame types are available on request.



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